



RECEIVED

OCT 14 2004

Technology Center 2600

ABSTRACT OF THE DISCLOSURE

A wafer pattern observation method provides CAD data corresponding to a pattern formed on a wafer. Control points for the wafer pattern are determined in accordance with an analysis of the CAD data. Coordinate data is acquired for the control points. An observational field of view of a pattern observation device is sequentially positioned to observation positions on the patterns in accordance with the acquired coordinate data to obtain image data for the observation positions on the patterns.